A PARTNER YOU CAN COUNT ON.
QUALITY YOU CAN TRUST.

THROUGHOUT YOUR PROJECT LIFECYCLE

JBC Technologies

3M Preferred Converter

Tackle your EMI/RFI shielding and grounding challenges with go-to adhesives from 3M and precision die-cutting from JBC Technologies.

With numerous high-speed, rotary die-cutting presses and the ability to fabricate intricate multi-layer parts with tight tolerances, JBC Technologies is the right choice for converted EMI/RFI shielding tapes and films.

Our seasoned process engineers have years of experience solving complex manufacturing problems, creating repeatable processes for difficult parts, and offering part presentations that offer the most value for the customer.

Here are just a few examples of part presentations we can provide for EMI/RFI shielding tapes:

- Slit to custom widths
- Kiss cut to a liner
- Island placed on a liner
- Pull tab for ease of assembly
- Individually cut
- Adhered to customer supplied plastic injected parts
- Indexed on a roll for automation

ELECTRICALLY CONDUCTIVE TAPES – QUICK REFERENCE GUIDE

We've prepared this quick reference guide for reference as you evaluate the samples in your kit. In order to ensure you choose the correct tape for your application, however, we strongly encourage you to collaborate directly with our team during the material selection and prototyping process. Contact us today at sales@jbc-tech.com.

Product	Available Tape Thickness mil (mm)	Conduction Path (XYZ or Z)	Conducive Filler Type	Electrical Resistance through Z-axis Ω (3M ETM-12)	Electrical Resistance through XY-axis Ω (3M ETM-7)	Key Features and Benefits
3M tape 3304BC-S	1.8 (.045)	XYZ	Ni/Cu Nonwoven Foil Backing	–	0.05 Ω	Single-sided, Best EMI shielding & grounding performance, single-sided, low contact resistance (R), excellent conformability
3M tape 9711S	2 (0.050), 4 (0.1), 6 (0.152), 8 (0.2)	XYZ	Ni/Cu woven (fabric)	0.02 ~ 0.08 Ω 0.04 - 0.9 Ω < 0.1 Ω	0.15~0.2 Ω 0.1 Ω 0.15 Ω 0.2 Ω	Double-sided, high adhesion, conformable (less flexible), low contact R quick bonding
3M tape 9707	2 (0.050)	XYZ	Silver particles	0.03 Ω	20~80 Ω	Adhesive transfer tape, high adhesion, low contact R, thermal conductivity, extremely conformable and best for flex circuit small "well" depth, resistance to shear stress
3M tape 9703	2 (0.050)	Z	Silver particles	0.01 Ω	NA	Adhesive transfer tape, Z-axis, low outgassing, extremely conformable, thermal conductivity
3M tape 9719	4 (0.1)	XYZ	Ni/C Nonwoven	10 Ω	15-30 Ω	Adhesive transfer tape, best peel strength for LSE substrates (converters laminating to conductive foam), higher temperature resistance, silicone adhesive

The tapes included in your kit are the products that have been selected by 3M as the highest performing "go-to" solutions. If these are not a fit for your application, please reach out, as there are additional options available. We'll work with you to determine which will best suit your needs.